

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (canceled).

Claim 2 (currently amended): The package of claim ~~[[1]]~~ 4, wherein the laser die comprises a first metal pad and the lid comprises a second metal pad on an inner surface, the first soft metal being disposed between the first and the second metal pads.

Claim 3 (currently amended): The package of claim ~~[[1]]~~ 4, wherein ~~the soft metal is the first and the second soft metals are~~ selected from the group consisting of indium, gallium, mercury and tin/lead solder.

Claim 4 (currently amended): A laser package, comprising:

a submount;

~~The package of claim 1, further comprising:~~

a laser die and a laser driver die mounted on the a first surface of the submount; and

a lid mounted on the first surface of the submount over the laser die and the laser driver die;

a first soft metal disposed between the laser die and the lid, the first soft metal conducting heat between the laser die and the lid;

another a second soft metal disposed between the laser driver die and the lid, wherein said another the second soft metal conducts conducting heat between the laser driver die and the lid, wherein the first and the second soft metals cold flow faster than the laser die and the lid can thermally cycle.

Claim 5 (currently amended): The package of claim 4, wherein the laser driver die comprises a first metal pad and the lid comprises a second metal pad on an inner surface, ~~said another the~~ second soft metal being disposed between the first and the second metal pads.

Claim 6 (currently amended): A laser package, comprising:

a submount;

~~The package of claim 1, further comprising:~~

a laser die and a photodetector die mounted on the first a surface of the submount; and
a lid mounted on the surface of the submount over the laser die and the photodetector die;
a first soft metal disposed between the laser die and the lid, the first soft metal conducting
heat between the laser die and the lid;
another a second soft metal disposed between the photodetector die and the lid, wherein
said another the second soft metal conducts conducting heat between the photodetector die
and the lid, wherein the first and the second soft metals cold flow faster than the laser die
and the lid can thermally cycle.

Claim 7 (currently amended): The package of claim 6, wherein the photodetector die comprises a first metal pad and the lid comprises a second metal pad on an inner surface, ~~said another the~~ second soft metal being disposed between the first and the second metal pads.

Claim 8 (currently amended): The package of claim [[1]] 4, further comprising a lens mounted on a second surface of the submount and opposite of the laser die.

Claim 9 (currently amended): The package of claim [[1]] 4, further comprising alignment pins mounted on a second surface of the submount.

Claim 10 (currently amended): A laser package, comprising:

a submount;

a laser die mounted on a surface of the submount;

a lid mounted on the surface of the submount over the laser die.

~~The package of claim 1, further comprising a thermal electric cooler mounted between on~~ an inner surface of the lid and the soft metal;

a soft metal disposed between the laser die and the thermal electric cooler, wherein the
soft metal conducts heat between the laser die and the thermal electric cooler, the thermal
electric cooler conducts heat between the soft metal and the lid, and the soft metal cold
flows faster than the laser die and the lid can thermally cycle.

Claim 11 (canceled).

Claim 12 (currently amended): The method of claim [[11]] 14, wherein ~~the soft metal is the first~~ and the second soft metals are selected from the group consisting of indium, gallium, mercury and tin/lead solder.

Claim 13 (currently amended): The method of claim ~~[[11]]~~ 14, wherein the laser die comprises a first metal pad, the method further comprising forming a second metal pad on the lid, wherein the first soft metal is disposed between the first and the second metal pads.

Claim 14 (currently amended): A method for forming a laser package, comprising:

~~The method of claim 11, further comprising:~~

mounting a laser die and a laser driver die on the a first surface of the a submount;

placing ~~another soft metal~~ first and second soft metals on the a lid; and

~~wherein said another~~ mounting the lid on the first surface of the submount, wherein the first soft metal is disposed between the laser die and the lid, the second soft metal is disposed between the laser driver die and the lid, after said mounting the lid on the submount and the first and the second soft metals cold flow faster than the laser die and the lid can thermally cycle.

Claim 15 (currently amended): The method of claim 14, wherein the laser driver die comprises a first metal pad, the method further comprising forming a second metal pad on the lid, wherein ~~said another~~ the second soft metal is disposed between the first and the second metal pads.

Claim 16 (currently amended): A method for forming a laser package, comprising:

~~The method of claim 11, further comprising:~~

mounting a laser die and a photodetector die on the first a surface of the a submount;

placing ~~another soft metal~~ first and second soft metals on the a lid; and

~~wherein said another~~ mounting the lid on the surface of the submount, wherein the first soft metal is disposed between the laser die and the lid, the second soft metal is disposed between the photodetector die and the lid, after said mounting the lid on the submount and the first and the second soft metals cold flow faster than the laser die and the lid can thermally cycle.

Claim 17 (currently amended): The method of claim 16, wherein the photodetector die comprises a first metal pad, the method further comprising forming a second metal pad on the lid, wherein ~~said another~~ the second soft metal is disposed between the first and the second metal pads.

Claim 18 (currently amended): The method of claim ~~[[11]]~~ 14, further comprising mounting a lens on a second surface of the submount and opposite of the laser die.

Claim 19 (currently amended): The method of claim ~~[[11]]~~ 14, further comprising mounting alignment pins on a second surface of the submount.

Claim 20 (currently amended): A method for forming a laser package, comprising:

mounting a laser die on a surface of a submount;

The method of claim 11, further comprising mounting a thermal electric cooler between
on an inner surface of the lid and the soft metal;

placing a soft metal on the thermal electric cooler; and

mounting the lid on the surface of the submount, wherein the soft metal is disposed
between the laser die and the thermal electric cooler, the thermal electric cooler is
disposed between the soft metal and the lid, and the soft metal cold flows faster than the
laser die and the lid can thermally cycle.